

ABSTRACT OF THE DISCLOSURE

5 A package with an integral window for housing a microelectronic device. The
integral window is bonded directly to the package without having a separate layer of
adhesive material disposed in-between the window and the package. The device can
be a semiconductor chip, CCD chip, CMOS chip, VCSEL chip, laser diode, MEMS
device, or IMEMS device. The package can be formed of a multilayered LTCC or
10 HTCC cofired ceramic material, with the integral window being simultaneously joined to
the package during cofiring. The microelectronic device can be flip-chip interconnected
so that the light-sensitive side is optically accessible through the window. A glob-top
encapsulant or protective cover can be used to protect the microelectronic device and
electrical interconnections. The result is a compact, low profile package having an
15 integral window that is hermetically sealed to the package prior to mounting and
interconnecting the microelectronic device.